

SEMICONDUCTOR PACKAGE STRUCTURE HAVING HOLLOW CHAMBER AND BOTTOM SUBSTRATE AND PACKAGE PROCESS THEREOF

ABSTRACT

A semiconductor package structure having hollow chamber includes a bottom substrate having a bottom baseboard and a bottom metal layer formed on a disposing area of the bottom baseboard, a connection layer formed on the bottom metal layer, and a top substrate. The bottom metal layer has at least one corner having a first and a second outer lateral surface, and an outer connection surface. A first extension line is formed from a first extreme point of the first outer lateral surface, and a second extension line is formed from a second extreme point of the second outer lateral surface. A first exposing area of the bottom baseboard is formed by connecting the first and second extreme points and a cross point of the first and second extension lines. The top substrate connects to the connection layer to form a hollow chamber between the top and bottom substrates.

FIG. 4